

General Description

The AO8818 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V while retaining a 12V $V_{GS(MAX)}$ rating. It is ESD protected. This device is suitable for use as a uni-directional or bi-directional load switch, facilitated by its common-drain configuration. AO8818 is Pb-free (meets ROHS & Sony 259 specifications).

Features

$$V_{DS} (V) = 30V$$

$$I_D = 7A (V_{GS} = 10V)$$

$$R_{DS(ON)} < 18m\Omega (V_{GS} = 10V)$$

$$R_{DS(ON)} < 20m\Omega (V_{GS} = 4.5V)$$

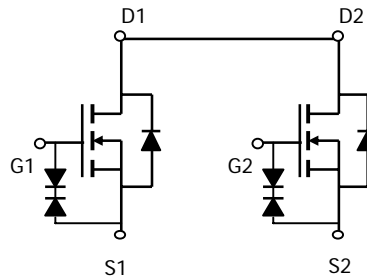
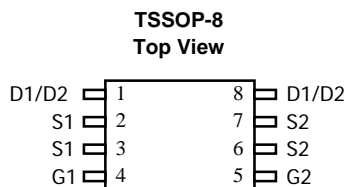
$$R_{DS(ON)} < 21m\Omega (V_{GS} = 4V)$$

$$R_{DS(ON)} < 24m\Omega (V_{GS} = 3.1V)$$

$$R_{DS(ON)} < 27m\Omega (V_{GS} = 2.5V)$$

$$R_{DS(ON)} < 58m\Omega (V_{GS} = 1.8V)$$

ESD Rating: 1500V HBM



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^A	I_D	7	A
		5.5	
Pulsed Drain Current ^B	I_{DM}	30	
Power Dissipation ^A	P_D	1.5	W
		0.96	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	64	83	$^\circ C/W$
Maximum Junction-to-Ambient ^A		89	120	$^\circ C/W$
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	53	70	$^\circ C/W$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =24V, V _{GS} =0V T _J =55°C			1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±10V			10	μA
BV _{GSO}	Gate-Source Breakdown Voltage	V _{DS} =0V, I _G =±250μA	±12			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.6	0.94	1.5	V
I _{D(ON)}	On state drain current	V _{GS} =4.5V, V _{DS} =5V	30			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =7A T _J =125°C	11.5 16	15 21	18 25	mΩ
		V _{GS} =4.5V, I _D =5A	13	17	20	mΩ
		V _{GS} =4V, I _D =5A	13.5	17.5	21	
		V _{GS} =3.1V, I _D =5A	15	19.5	24	
		V _{GS} =2.5V, I _D =4A	17	22	27	mΩ
		V _{GS} =1.8V, I _D =3A	35	45	58	
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =7A		45		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.74	1	V
I _S	Maximum Body-Diode Continuous Current				2.5	A
DYNAMIC PARAMETERS						
C _{ISS}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, f=1MHz		880	1060	pF
C _{OSS}	Output Capacitance			130		pF
C _{RSS}	Reverse Transfer Capacitance			90		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		1.3	2	Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =15V, I _D =7A		11.6	14	nC
Q _{gs}	Gate Source Charge			1.9		nC
Q _{gd}	Gate Drain Charge			4.6		nC
t _{D(on)}	Turn-On Delay Time	V _{GS} =5V, V _{DS} =15V, R _L =2.2Ω, R _{GEN} =3Ω		8.7		ns
t _r	Turn-On Rise Time			13.7		ns
t _{D(off)}	Turn-Off Delay Time			36		ns
t _f	Turn-Off Fall Time			11		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =7A, dI/dt=100A/μs		16	20	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =7A, dI/dt=100A/μs		7.7		nC

A: The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

D: The static characteristics in Figures 1 to 6,12,14 are obtained using <300 μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

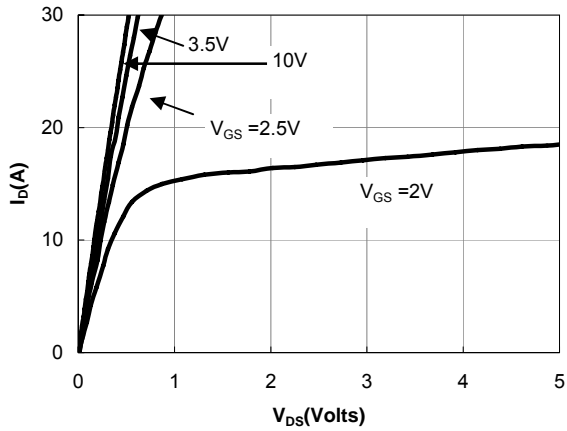


Figure 1: On-Regions Characteristics

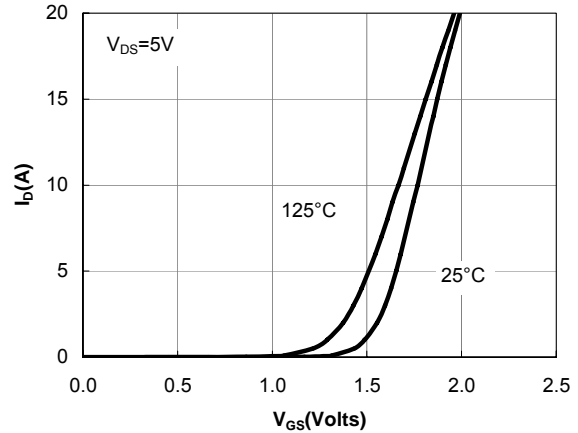


Figure 2: Transfer Characteristics

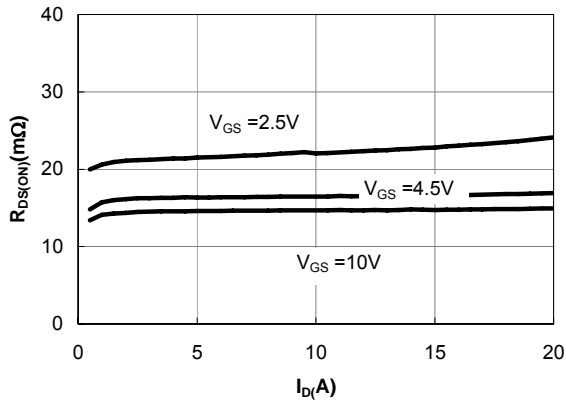


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

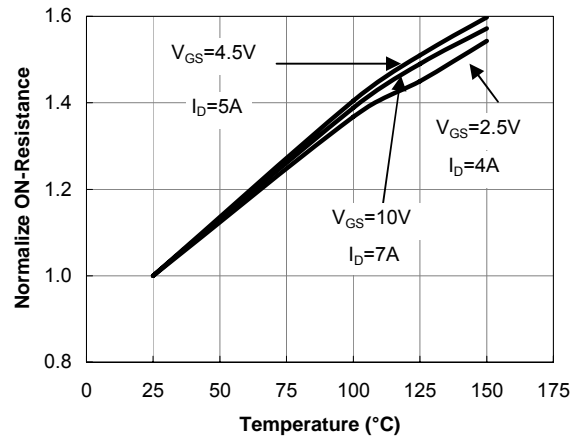


Figure 4: On-Resistance vs. Junction Temperature

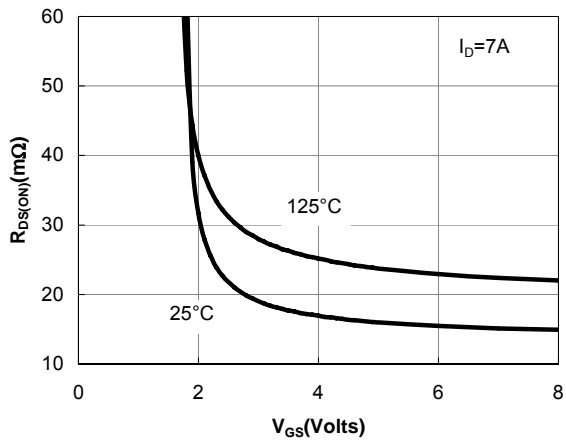


Figure 5: On-Resistance vs. Gate-Source Voltage

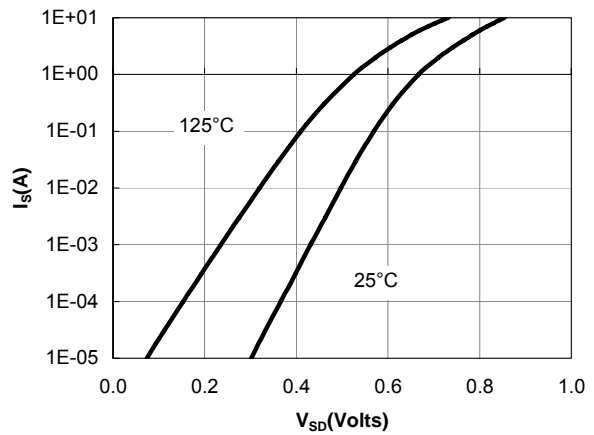


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

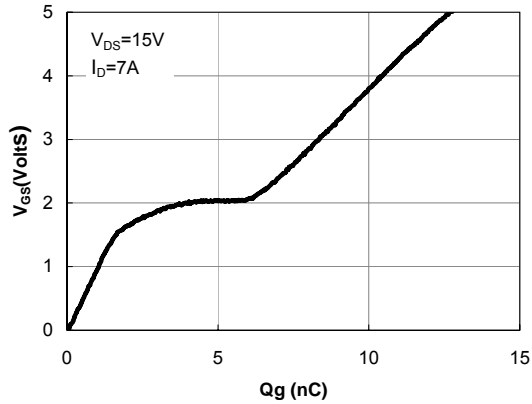


Figure 7: Gate-Charge Characteristics

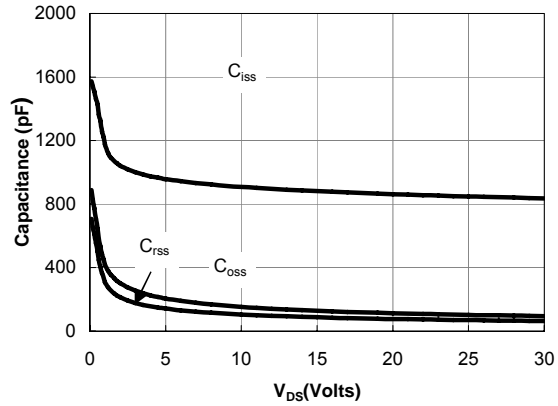


Figure 8: Capacitance Characteristics

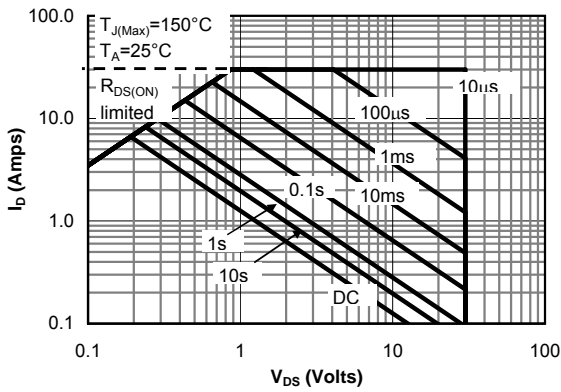


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

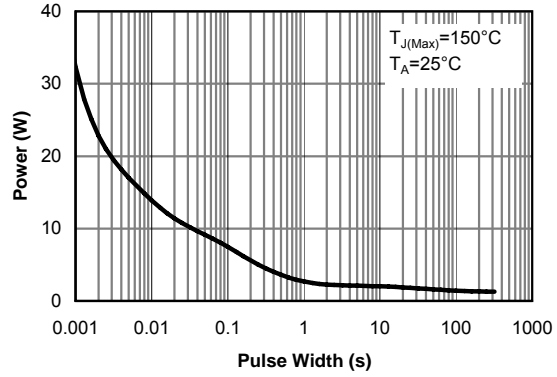


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

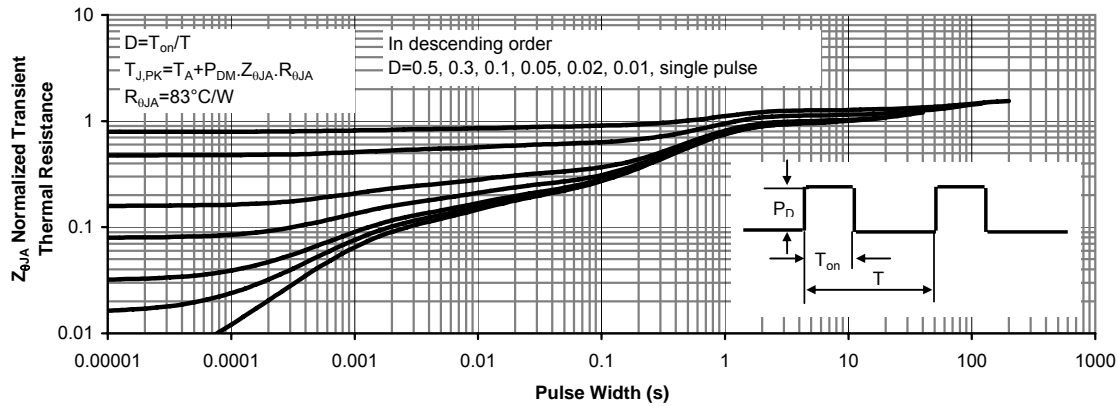


Figure 11: Normalized Maximum Transient Thermal Impedance